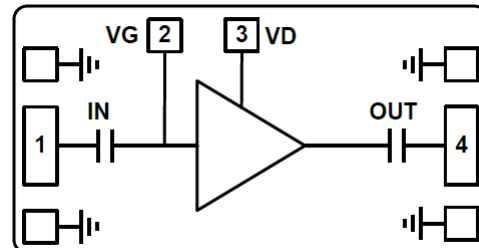


Features

- Two operating mode: high power consumption and low power consumption
- Frequency: 18-40GHz
- Noise Figure: 2.3dB@27mA, 2.2dB@16mA
- Gain: 15dB@27mA, 13dB@16mA
- P1dB: 12dBm@27mA, 8dBm@16mA
- Power Supply: +5V@27mA, VG is floating
- +5V@16mA, VG connected to GND
- Input/Output: 50Ω
- Die Size: 1.5 x 0.8 x 0.1 mm

Functional Block Diagram



Typical Applications

- Test Instrumentation
- Microwave Radio & VSAT
- Military & Space
- Telecom Infrastructure
- Fiber Optics

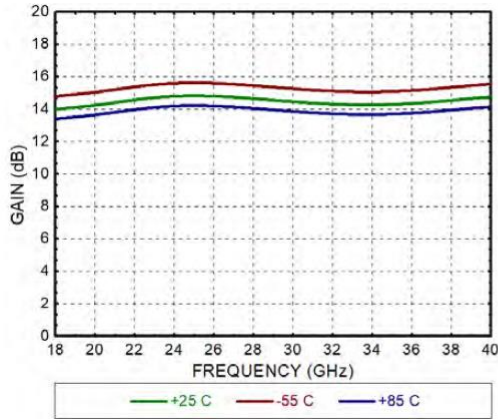
Electrical Specifications

TA = +25°C, VDD=+5V

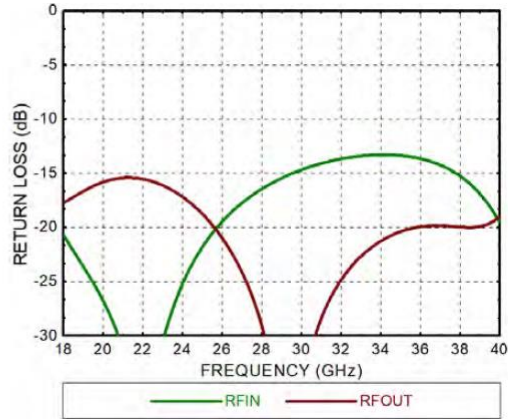
Parameters	VG is floating			VG connected to GND			Units
	Min.	Typ.	Max.	Min.	Typ.	Max.	
Frequency	18-40			18-40			GHz
Gain		15			13		dB
Gain Flatness		±0.4			±0.3		dB
Input Return Loss		15			13		dB
Output Return Loss		15			15		dB
Output 1dB Compression (P1dB)		12			8		dBm
Psat		14			10		dBm
Output IP3		22			18		dBm
Noise Figure		2.3			2.2		dB
Operating current	18	27	40	10	16	25	mA



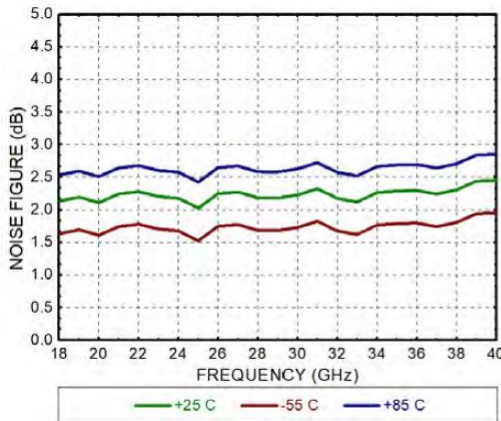
Gain (VG is floating)



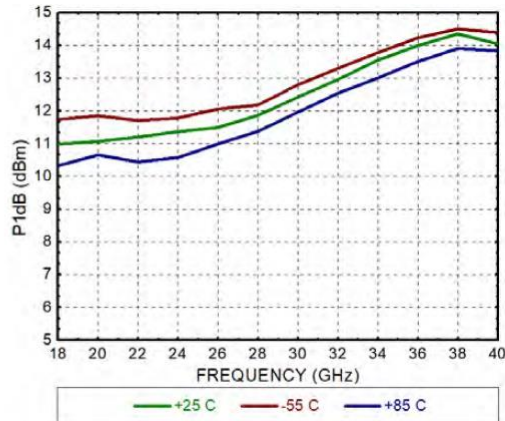
Return Loss (VG is floating)



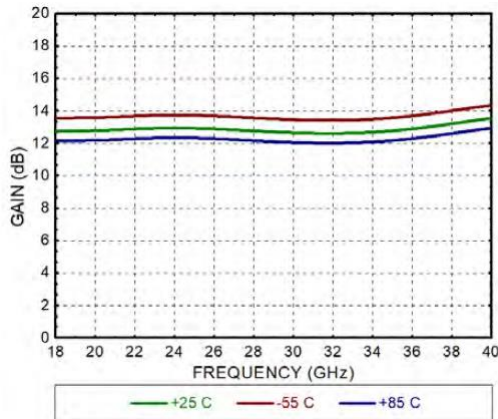
Noise Figure (VG is floating)



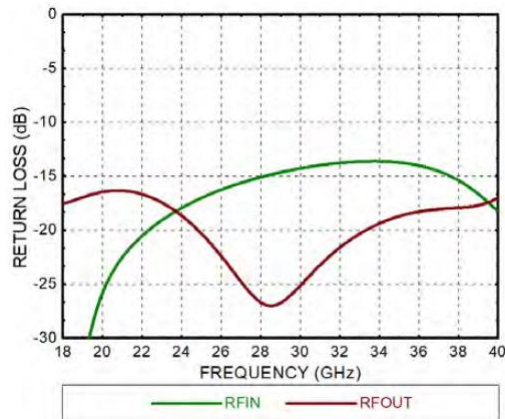
P1dB (VG is floating)



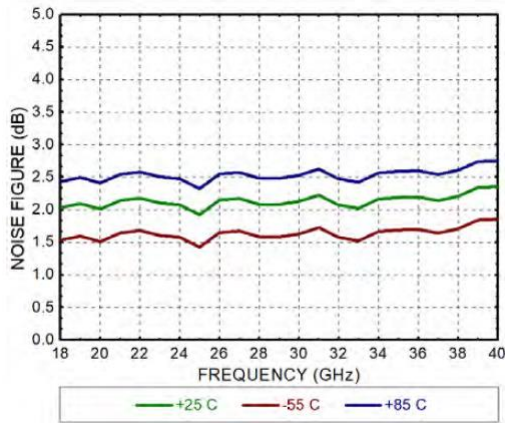
Gain (VG connected to GND)



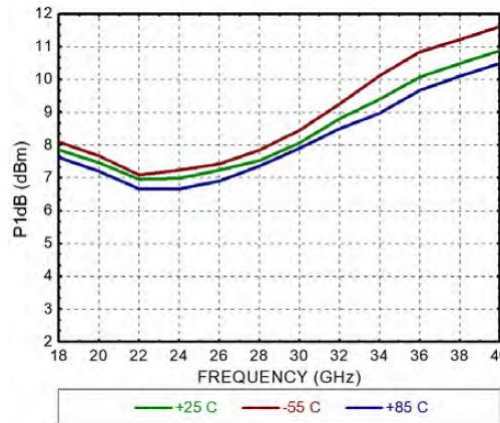
Return Loss (VG connected to GND)



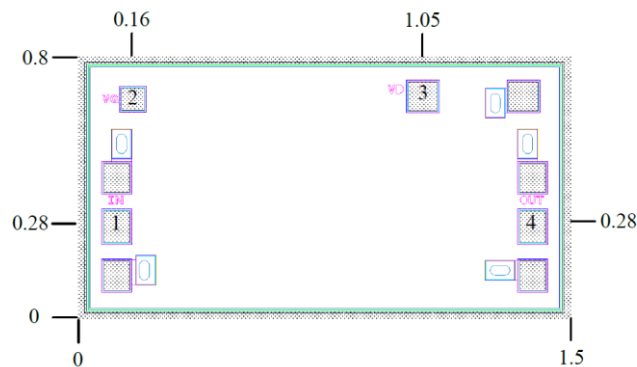
Noise Figure (VG connected to GND)



P1dB(VG connected to GND)



Outline Drawing:
All Dimensions in mm

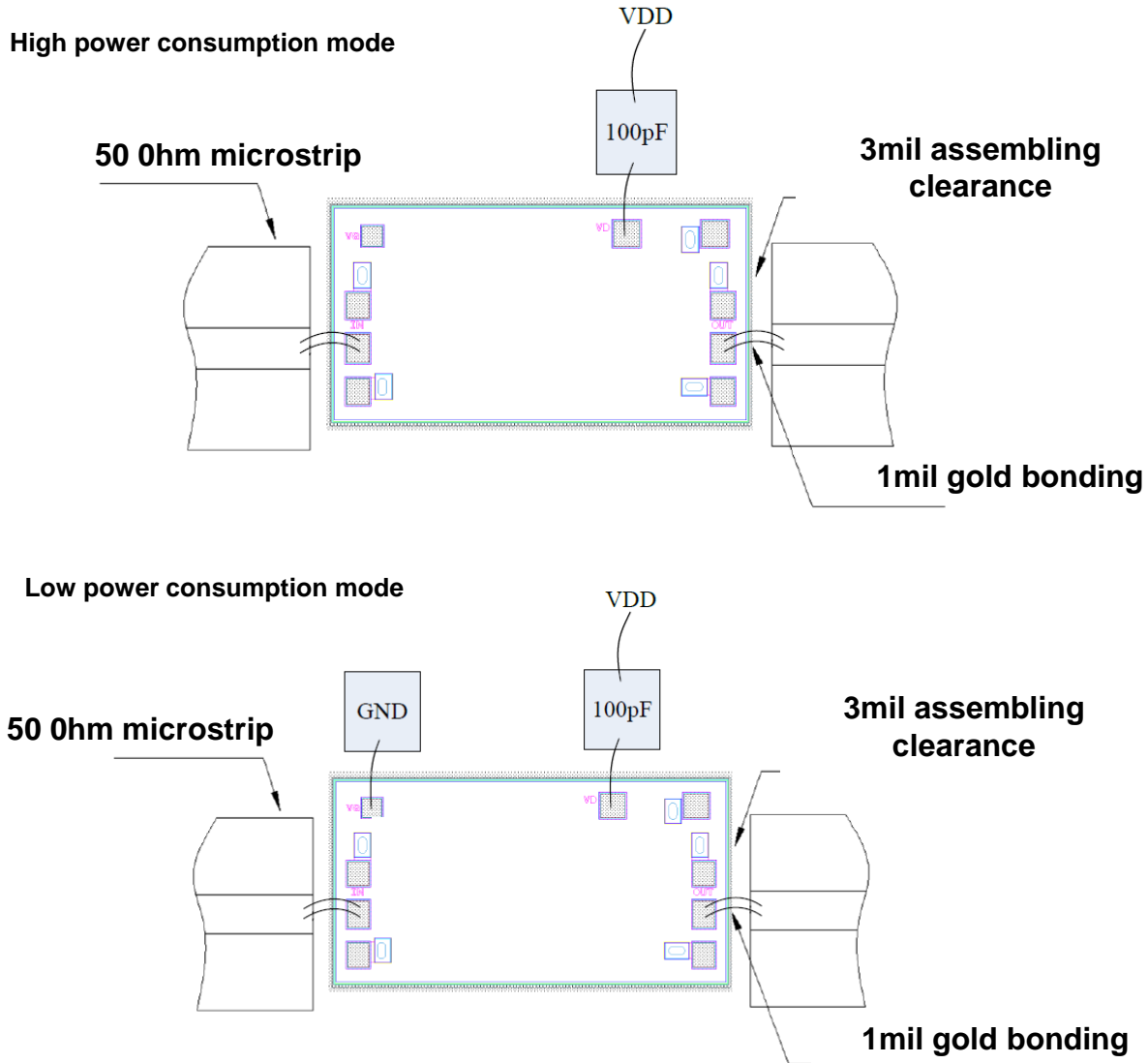


Pad Description

PAD	Function	Description
1	IN	This pad is AC coupling, 50 ohm matched.
2	VG	This pad determines the die's operating mode. When floating, it's high power consumption mode. When connected to RF/DC GND, it's low power consumption mode.
3	VD	This pad provides power supply for the amplifier. It should be connected to extra 100pF bypass capacitor.
4	OUT	This pad is AC coupling, 50 ohm matched.
Die Bottom	GND	Die backside must connect to RF/DC GND.



Assembly Drawing



Notes:

1. Die thickness: 100um
2. Typical bond pad is 100*80 μm^2
3. Bond pad metalization: Gold
4. Backside metalization: Gold
5. Backside of the die (GND)
6. No connection required for unlabeled bond pads

Maximum Ratings:

1. Maximum drain voltage: +6V
2. Maximum input power: +15dBm
3. Operating temperature: -55°C to +85°C
4. Storage temperature: -65°C to +150°C